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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.
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09/176,422 10/21/98 WILK

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EXAMINER

BEREZNY, N

ART UNIT

PAPER NUMBER

2823

DATE MAILED:

06/05/01

Please find below and/or attached an Office communication concerning this application or proceeding.

Commissioner of Patents and Trademarks

Office Action Summary

Application No.

09/176,422

Applicant(s)

WILK ET AL.

Examiner

Neal Berezny

Art Unit

2823

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136 (a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 12 March 2001.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-25 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 1-25 is/are rejected.
- 7) ☒ Claim(s) 23-25 is/are objected to.
- 8) ☐ Claims _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are objected to by the Examiner.
- 11) ☐ The proposed drawing correction filed on _____ is: a) ☐ approved b) ☐ disapproved.
- 12) ☐ The oath or declaration is objected to by the Examiner.

Priority under 35 U.S.C. § 119

- 13) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. _____.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- * See the attached detailed Office action for a list of the certified copies not received.
- 14) ☒ Acknowledgement is made of a claim for domestic priority under 35 U.S.C. § 119(e).

Attachment(s)

- 15) ☐ Notice of References Cited (PTO-892)
- 16) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 17) ☐ Information Disclosure Statement(s) (PTO-1449) Paper No(s) _____
- 18) ☐ Interview Summary (PTO-413) Paper No(s) _____
- 19) ☐ Notice of Informal Patent Application (PTO-152)
- 20) ☐ Other: _____

DETAILED ACTION - NON-FINAL

Claim Rejections - 35 USC § 112

1. The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

2. Claims 1-25 are rejected under 35 U.S.C. 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to enable one skilled in the art to which it pertains, or with which it is most nearly connected, to make and/or use the invention. Independent claims 1 and 18 contain the limitation, "creating a first uniformly thick, gate oxide film". In applicant's appeal, p.8, ln.3-6, applicant's representative admits that ordinary artisans would not succeed in using Nayar to produce a uniformly thick gate oxide. Since the Nayar process is identical to the claimed process, allegedly with the exception of forming a uniformly thick gate oxide, the disclosure fails to enable one of ordinary skill to produce the claimed limitation of a uniform gate oxide from the claimed process. Applicant need not enable every element of the claims if the element is admittedly well known in the art and would be obvious to one of ordinary skill in the art at the time of the invention. However, if such an element is critical and the basis of patentability, then applicant would be estopped from asserting that the element is both non-obvious, with regard to patentability, and also obvious, with regard to disclosure, and need not be fully disclosed.

3. Claims 1-17, and 23 are rejected under 35 U.S.C. 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to enable one skilled in the art to which it pertains, or with which it is most nearly connected, to make and/or use the invention. Independent claim 1 contains the limitation of providing a substrate with a "clean atomically flat, silicon surface".

Applicant's representative admits that ordinary artisans would not expect to be able to form a Silicon substrate that is atomically flat, see appeal, p.6, ln.25-28, yet nowhere in the specifications does applicant teach how one of ordinary skill in the art would be able to obtain an atomically flat Si substrate. Applicant need not enable every element of the claims if the element is admittedly well known in the art and would be obvious to one of ordinary skill in the art at the time of the invention. However, if such an element is critical and the basis of patentability, then applicant would be estopped from asserting that the element is both non-obvious, with regard to patentability, and also obvious, with regard to disclosure, and need not be fully disclosed.

4. Claims 23-25 are rejected under 35 U.S.C. 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to enable one skilled in the art to which it pertains, or with which it is most nearly connected, to make and/or use the invention. In each of the claims, 23-25, a limitation is asserted that the claimed process produces breakdown voltages greater than 10 MV/cm or 12 MV/cm. Applicants admit that a process that used the steps in the claim to make a gate

oxide with a breakdown strength of 8 MV/cm would infringe on claim 18 but not claim 24, see appeal p.5, ln.25-28. But neither the claims nor the specifications disclose any process variations that would enable one of ordinary skill in the art to achieve any deviation or control of breakdown voltages. Further, applicant's representative admits that Nayar does not suggest to an ordinary artisan a means of producing breakdown voltages greater than 10 MV/cm or 12 MV/cm, see appeal p.6, ln.2-8, but the process taught by Nayar has not been distinguished from the claimed process, except allegedly in terms of the properties of the final oxide product. By applicant's admission the claimed process is not enabled. Applicant need not enable every element of the claims if the element is admittedly well known in the art and would be obvious to one of ordinary skill in the art at the time of the invention. However, if such an element is critical and the basis of patentability, then applicant would be estopped from asserting that the element is both non-obvious, with regard to patentability, and also obvious, with regard to disclosure, and need not be fully disclosed.

5. Claim 6 is rejected under 35 U.S.C. 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to enable one skilled in the art to which it pertains, or with which it is most nearly connected, to make and/or use the invention. Applicants state that the Nayar article teaches a UV/ozone method and that one of ordinary skill in the art would not be able to use the Nayar method to produce the claimed limitation of "at least part of the atmosphere that does not contact the silicon surface includes an ozone plasma", see appeal, p.7, ln.13-17.

Art Unit: 2823

Neither the claims nor the specifications differentiate between any alleged differences between the prior art and the claimed invention, thereby not enabling one of ordinary skill in the art, by applicant's own admission. Applicant need not enable every element of the claims if the element is admittedly well known in the art and would be obvious to one of ordinary skill in the art at the time of the invention. However, if such an element is critical and the basis of patentability, then applicant would be estopped from asserting that the element is both non-obvious, with regard to patentability, and also obvious, with regard to disclosure, and need not be fully disclosed.

Claim Objections

6. Claims 23-25 are objected to under 37 CFR 1.75(c), as being of improper dependent form for failing to further limit the subject matter of a previous claim. Applicant is required to cancel the claim(s), or amend the claim(s) to place the claim(s) in proper dependent form, or rewrite the claim(s) in independent form. Claims 1 and 18 are process claims and claims 23-25 are merely observed properties of material produced by the claimed process, and therefore does not serve to limit or alter the process itself. Observed properties of the product cannot be patented, only the process that makes the product can be patented in this case.

Claim Rejections - 35 USC § 103

7. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

8. Claim 18 is rejected under 35 U.S.C. 103(a) as being unpatentable over Fujishiro et al. (5,294,571) in combination with Nayar et al. (Electronic Letters, 2/1/90, vol.26, no.3). Fujishiro teaches forming a partially completed integrated circuit (IC), fig.2, el.1 and 9, where the substrate surface is cleaned, col.7, ln.8-12, and then exposed in an ozone ambient, col.4, ln.65-67, to form a gate oxide, el.6, and then forming a gate electrode over the gate oxide, el.7. Fujishiro fails to teach conducting the oxide growth at a stable below 200 °C. Nayar anticipates growing an ultra-thin gate oxides, by UV formed ozone ambient, for microelectronic use, p.206, bottom of first col., after a surface cleaning. Nayar teaches using various stable temperatures, see fig.2, during exposure to an ozone ambient to obtain a thin high-grade oxide. It would be obvious to one of ordinary skill in the art to combine the teachings of Nayar with Fujishiro to form a low temperature gate oxide in Fujishiro's transistor by using stable temperatures, to form oxides of stable uniform thickness. Nayar provides the motivation to combine on page 205, col.1, start of paper, by pointing out the need to reduce the thermal budget, while maintaining control of the oxide growth rate, so as to avoid associated problems, such as wafer warpage and defect generation.

9. Claims 24-25 are rejected under 35 U.S.C. 103(a) as being unpatentable over Fujishiro and Nayar as applied to claims 1-13 above, and further in view of Wolf, vol.3,

Art Unit: 2823

p.422-423. Wolf teaches using a gate oxide in excess of 8 MV/cm, p.422, characteristic #4. It would be obvious to one of ordinary skill in the art to combine Wolf with Fujishiro and Nayar in order to reduce dielectric breakdown of the gate oxide to reduce catastrophic failure of the device.

10. Claims 1-13 are rejected under 35 U.S.C. 103(a) as being unpatentable over Fujishiro and Nayar as applied to claim 18 above, and in view of Choquette et al. (5,275,687). In addition to the teaching described above Nayar also teaches the conversion of molecular oxygen to ozone with the use of UV light, see p.205, col.2, first two chemical equations. Also taught by Nayar in the same equations is the use of an inert ambient in addition to the ozone. Further, Fujishiro also teaches keeping the ozone plasma not at the Si surface, col.5, ln.28-40.

11 Fujishiro and Nayar appear not to specifically state that the Si surface should be atomically flat. Choquette teaches a process to create an atomically flat or smooth surface prior to the formation of a high quality epitaxial layer, see abstract. It would be obvious to one of ordinary skill in the art to combine Choquette with Fujishiro and Nayar to form an atomically flat Si surface prior to the formation of a very thin gate oxide layer. One of ordinary skill in the art at the time of the invention would have been motivated to provide an atomically flat surface before forming a gate oxide that is only 2 or 3 atoms thick. Clearly a surface with deviations greater than 1 or 2 atoms thick would increase

Art Unit: 2823

the likelihood of defects in the gate oxide resulting in an increase in the leakage current across the gate oxide layer.

12. Claim 23 is rejected under 35 U.S.C. 103(a) as being unpatentable over Fujishiro, Nayar, and Choquette as applied to claims 1-13 above, and further in view of Wolf, vol.3, p.422-423. Wolf teaches using a gate oxide in excess of 8 MV/cm, p.422, characteristic #4. It would be obvious to one of ordinary skill in the art to combine Wolf with Fujishiro, Nayar, and Choquette in order to reduce dielectric breakdown of the gate oxide to reduce catastrophic failure of the device.

13. Claim 19 is rejected under 35 U.S.C. 103(a) as being unpatentable over Fujishiro and Nayar as applied to claim 18 above, and in view of Cook et al. (5,194,397). Fujishiro and Nayar appear not to specifically state that the cleaned surface, prior to oxidation, be hydrogen terminated. Cook teaches the art of hydrogen terminating an exposed Si surface, col.3, ln.39-49. It would be obvious to one of ordinary skill in the art to combine Cook with Fujishiro and Nayar to hydrogen terminate the Si surface in order to passivate the surface to keep it clean and prevent unwanted or uncontrolled reaction with the silicon surface. This would help reduce defect densities in the subsequently formed gate oxide.

14. Claims 20-22 are rejected under 35 U.S.C. 103(a) as being unpatentable over Fujishiro and Nayar as applied to claim 18 above, and in view of Faraone et al.

Art Unit: 2823

(4,604,304) and Doklan et al. (4,851,370). Fujishiro and Nayar do not specifically teach the use of multiple layers of oxide for a thicker gate oxide layer. Faraone teaches forming a silicon layer on the first oxide and then oxidizing it for a thicker oxide, col.4, ln.39-42. It would be obvious to one of ordinary skill in the art to combine Faraone with Fujishiro and Nayar, to form a thicker two-layer gate oxide. Doklan teaches forming two oxide layers on top of each other to misalign the defects of each layer in order to reduce leakage current, thereby providing the motivation to combine Faraone and Doklan with Fujishiro and Nayar.

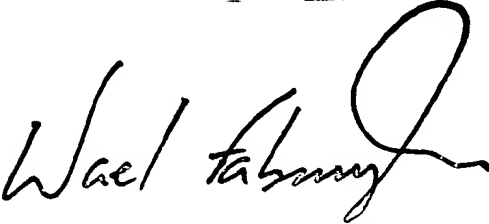
15. Claims 14-17 are rejected under 35 U.S.C. 103(a) as being unpatentable over Fujishiro, Nayar, and Choquette as applied to claims 1-13 above, and further in view of Faraone et al. (4,604,304) and Doklan et al. (4,851,370). Fujishiro and Nayar do not specifically teach the use of multiple layers of oxide for a thicker gate oxide layer. Faraone teaches forming a silicon layer on the first oxide and then oxidizing it for a thicker oxide, col.4, ln.39-42. It would be obvious to one of ordinary skill in the art to combine Faraone with Fujishiro, Nayar, and Choquette, to form a thicker two-layer gate oxide. Doklan teaches forming two oxide layers on top of each other to misalign the defects of each layer in order to reduce leakage current, thereby providing the motivation to combine Faraone and Doklan with Fujishiro, Nayar, and Choquette.

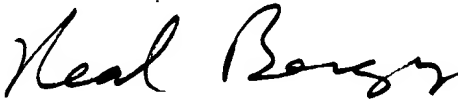
CONCLUSION

16. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Neal Berezny whose telephone number is (703) 305-1481. The examiner can normally be reached on Monday to Friday from 7:00 to 3:30.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy, can be reached at (703) 308-4918. The fax phone number for the organization where this application or proceeding is assigned is (703) 308-7724.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.


SUPERVISORY PRIMARY EXAMINER
TECHNOLOGY CENTER 2000


6-1-01

Neal Berezny

Patent Examiner

Art Unit 2823